ABSTRACT OF THE DISCLOSURE

A quartz oscillator is constructed to achieve a better yield when being mass-produced, by providing a margin of strength for each of the substrates thereof while reducing the thickness of the quartz oscillator devices. A box-shaped circuit substrate is provided for mounting thereon circuit components having different heights from one another. The bottom plate of a recess in this circuit substrate has a level difference, and is constituted of a region where the thickness of the bottom plate is relatively larger and a region where the thickness of the bottom plate is relatively smaller. High-profile circuit components are mounted on the region where the thickness of the bottom plate is smaller, while low-profile components are mounted on the region where the thickness of the bottom plate is larger. By thus increasing the thickness of one portion of the bottom plate of the circuit substrate, the bending strength of the circuit substrate is improved.